



Description

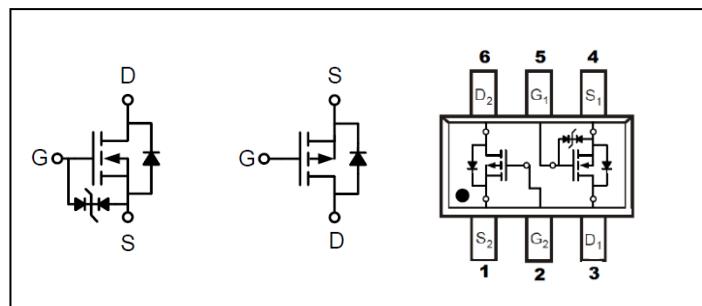
The HSSK8402 uses advanced trench technology to provide excellent RDS(ON), low gate charge and high density cell Design for ultra low on-resistance. This device is suitable for use as a load switch or in PWM applications.

Product Summary

BVDSS	RDSON	ID
65V	1.7Ω	0.13A
-55V	1Ω	-0.13A

- PWM applications
- Load switch

SOT-363 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		N-Channel	P-Channel	
V _{DS}	Drain-Source Voltage	65	-55	V
V _{GS}	Gate-Source Voltage	±20	±20	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	0.13	-0.13	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	0.1	-0.1	A
I _{DM}	Pulsed Drain Current ²	0.5	-0.5	A
P _D @T _A =25°C	Total Power Dissipation ⁴	0.38	0.38	W
T _{STG}	Storage Temperature Range	-55 to 150	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	415	°C/W



N-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	65	---	---	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_D=0.13\text{A}$	---	1.7	2.3	Ω
		$V_{\text{GS}}=4.5\text{V}$, $I_D=0.13\text{A}$	---	2.1	2.6	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1.0	1.5	2.0	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-5.24	---	$\text{mV}/^{\circ}\text{C}$
$I_{\text{DS}(\text{SS})}$	Drain-Source Leakage Current	$V_{\text{DS}}=48\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^{\circ}\text{C}$	---	---	1	μA
		$V_{\text{DS}}=48\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 10	μA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=30\text{V}$, $I_D=0.13\text{A}$	---	160	---	mS
Q_g	Total Gate Charge (4.5V)	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=0.13\text{A}$	---	0.6	---	nC
Q_{gs}	Gate-Source Charge		---	0.2	---	
Q_{gd}	Gate-Drain Charge		---	0.15	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=30\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=1\Omega$, $I_D=0.13\text{A}$	---	6.5	---	ns
T_r	Rise Time		---	12	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	13	---	
T_f	Fall Time		---	14	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	19	---	pF
C_{oss}	Output Capacitance		---	7.4	---	
C_{rss}	Reverse Transfer Capacitance		---	4.9	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_S=0.13\text{A}$, $T_J=25^{\circ}\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



P-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=-250\mu\text{A}$	-55	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=-10\text{V}$, $\text{I}_D=-0.13\text{A}$	---	1.0	1.8	Ω
		$\text{V}_{\text{GS}}=-4.5\text{V}$, $\text{I}_D=-0.13\text{A}$	---	1.2	2.0	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=-250\mu\text{A}$	-1.0	-1.5	-2.0	V
$\Delta \text{V}_{\text{GS(th)}}$	$\text{V}_{\text{GS(th)}}$ Temperature Coefficient		---	4.56	---	$\text{mV}/^{\circ}\text{C}$
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=-48\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=25^{\circ}\text{C}$	---	---	-1	μA
		$\text{V}_{\text{DS}}=-48\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=55^{\circ}\text{C}$	---	---	-5	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=-25\text{V}$, $\text{I}_D=-0.13\text{A}$	---	60	---	S
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=-15\text{V}$, $\text{V}_{\text{GEN}}=-5\text{V}$, $\text{R}_L=50\Omega$, $\text{I}_D=-0.13\text{A}$	---	2.1	---	ns
T_r	Rise Time		---	1.1	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	16	---	
T_f	Fall Time		---	8	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=-5\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	22	---	pF
C_{oss}	Output Capacitance		---	7.3	---	
C_{rss}	Reverse Transfer Capacitance		---	4	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_S=-1\text{A}$, $\text{T}_J=25^{\circ}\text{C}$	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
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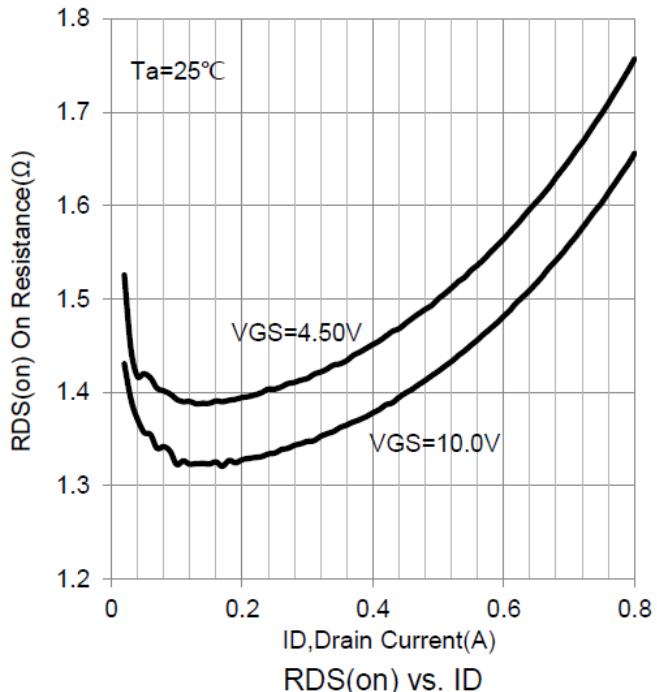
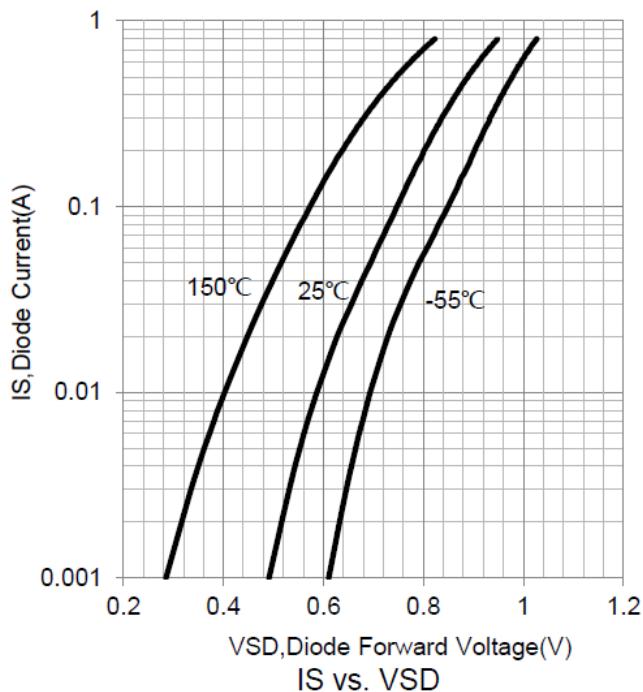
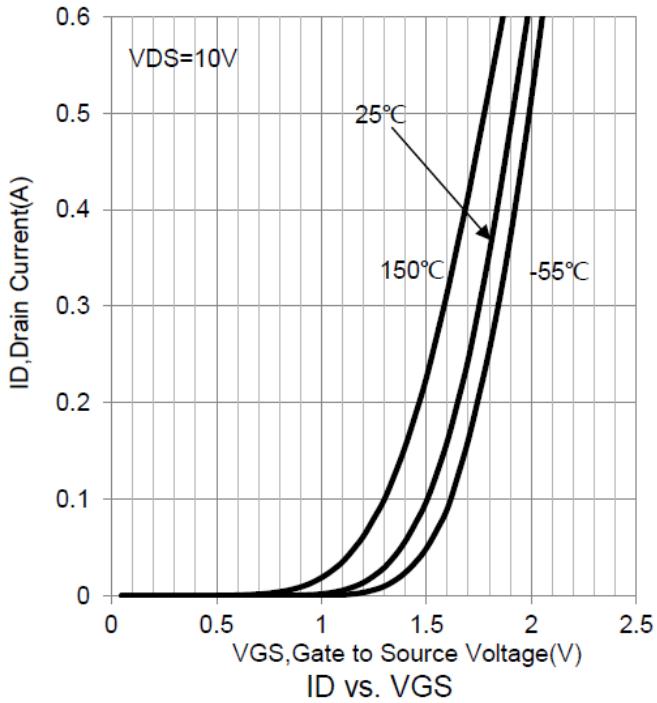
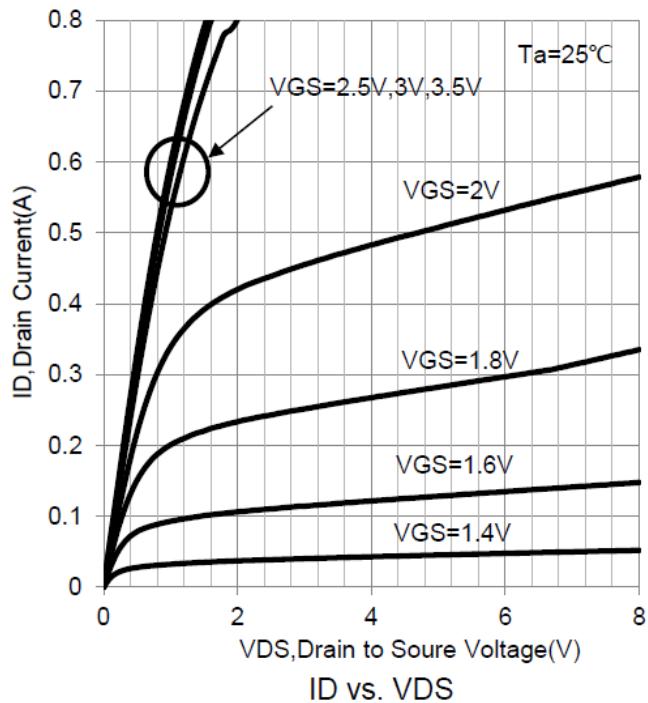


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HSSK8402

N-Ch and P-Ch Fast Switching MOSFETs

N-Channel Typical Characteristics

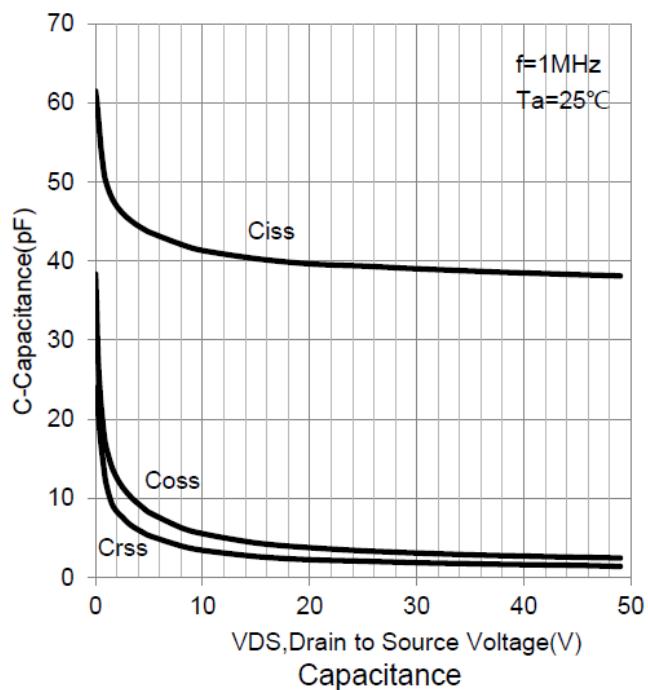
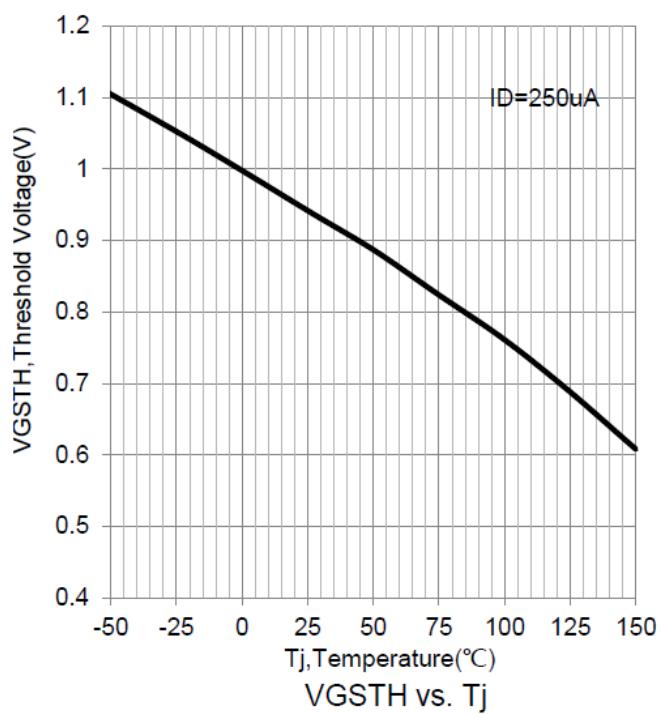
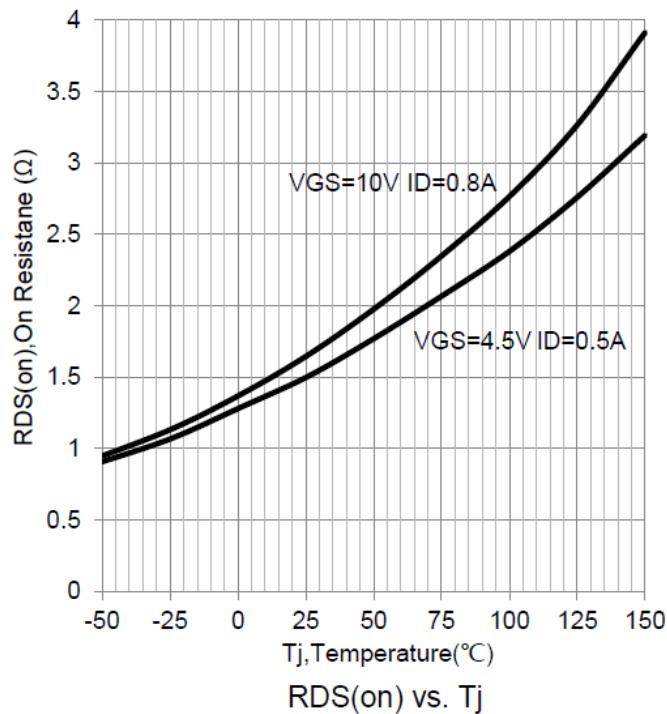




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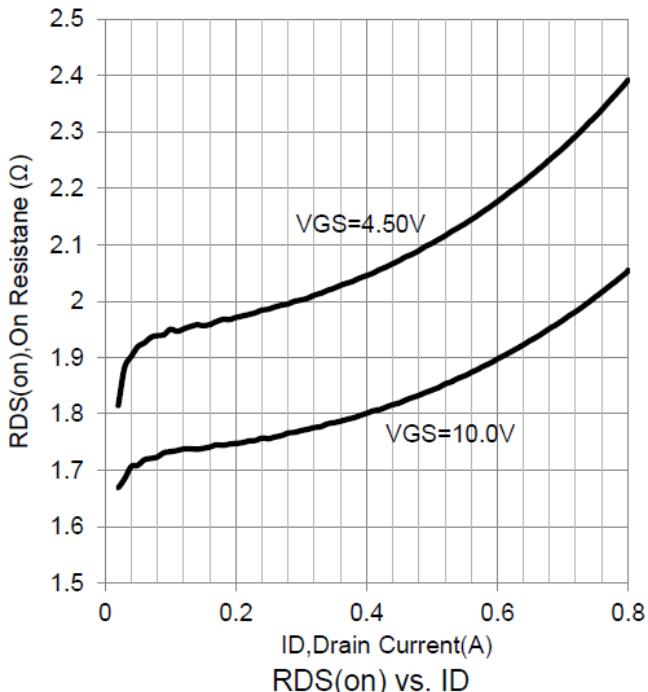
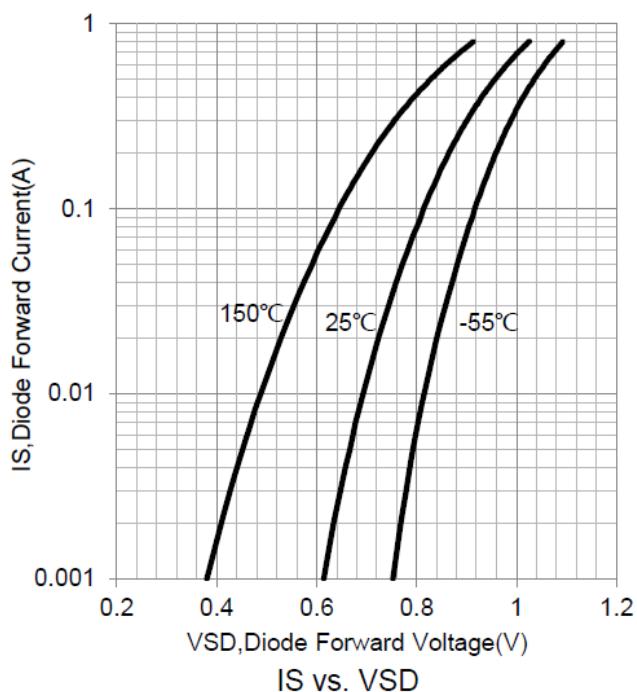
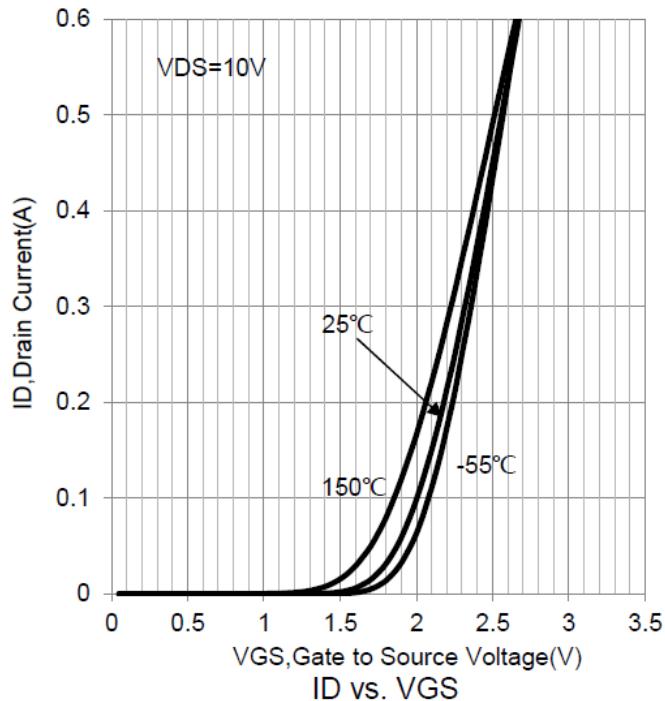
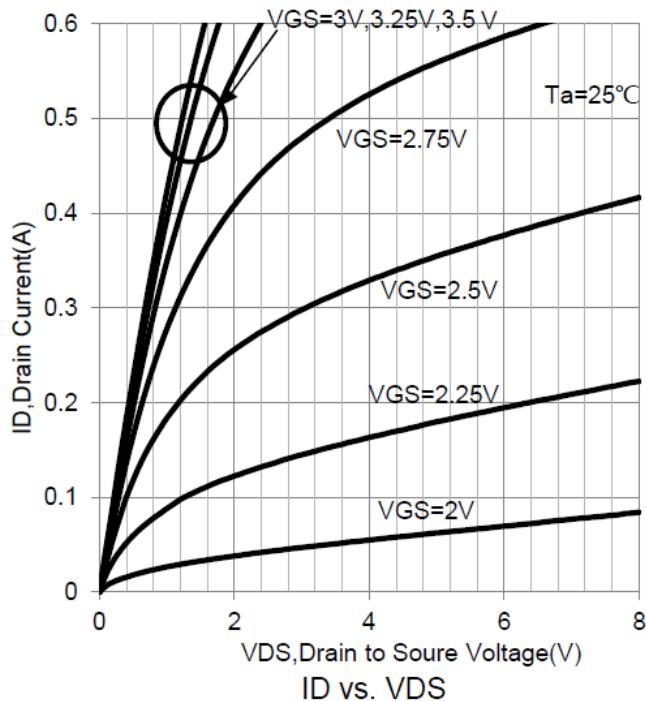
HSSK8402

N-Ch and P-Ch Fast Switching MOSFETs



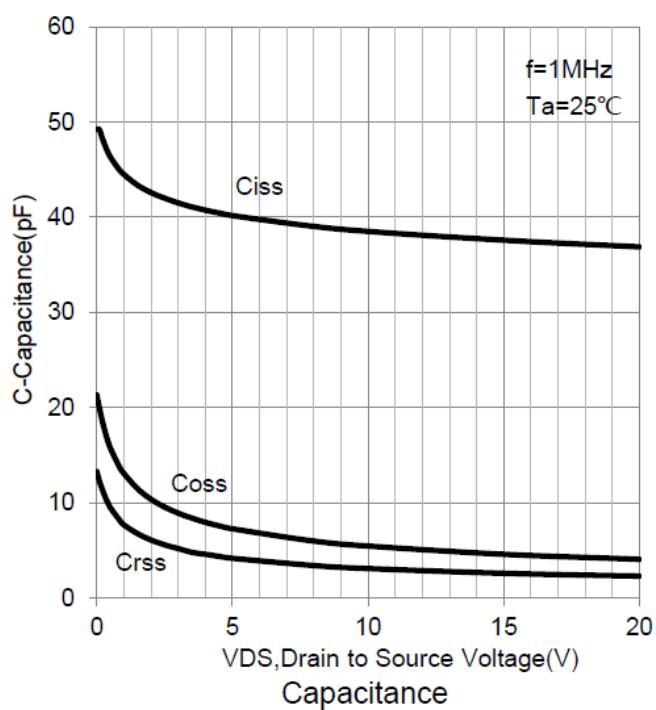
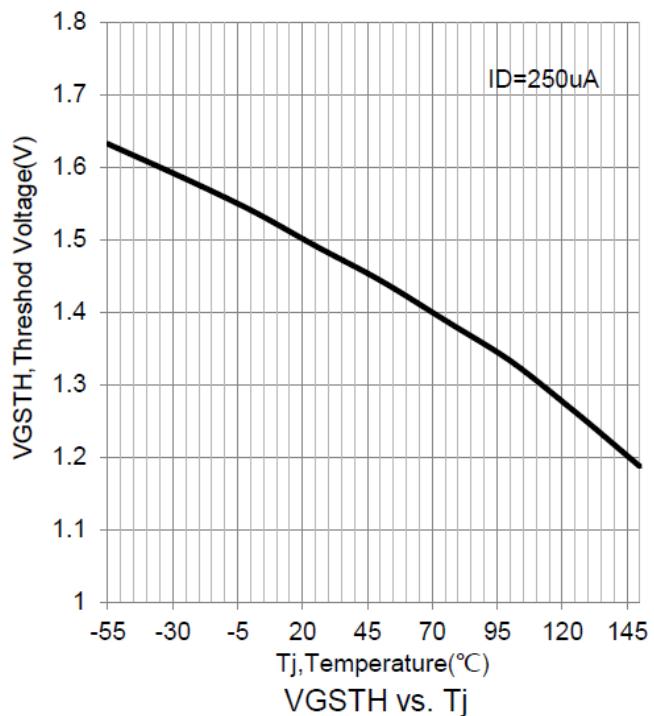
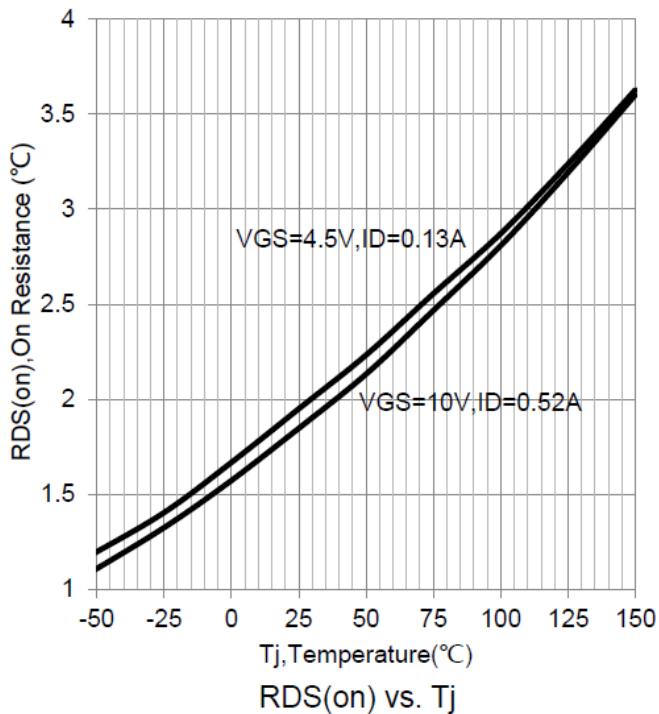


P-Channel Typical Characteristics





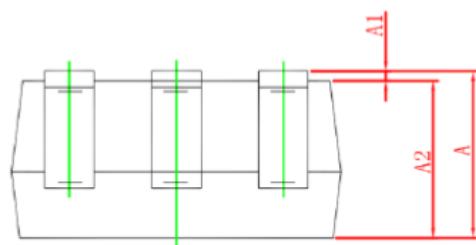
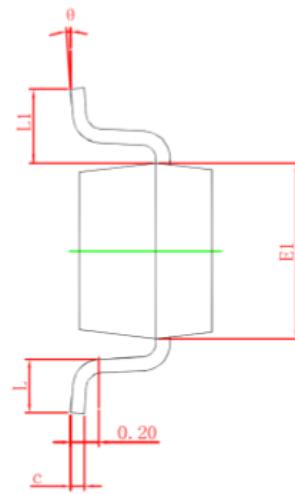
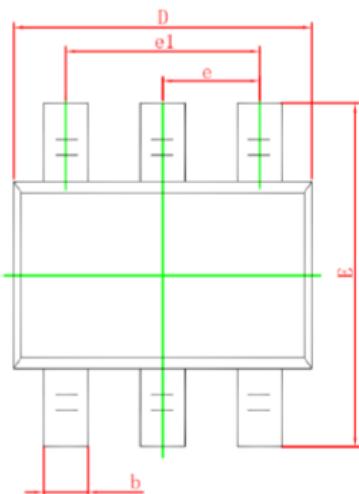
N-Ch and P-Ch Fast Switching MOSFETs





PACKAGE INFORMATION

- SOT-363



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	2.150	2.450	0.085	0.096
E1	1.150	1.350	0.045	0.053
e	0.650 TYP.		0.026 TYP.	
e1	1.200	1.400	0.047	0.055
L	0.260	0.460	0.010	0.018
L1	0.525 REF.		0.021 REF.	
θ	0°	8°	0°	8°

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